



(3)

PATENT
Attorney Docket No. SAM-134


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Jae-Hoon Lee, et al. Examiner: Not yet assigned
Serial No.: 09/737,540 Group Art Unit: 2811
Filing Date: December 15, 2000
Title: SEMICONDUCTOR DEVICE WIRING AND METHOD OF
MANUFACTURING THE SAME

CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.8

I hereby certify that this correspondence is being deposited with the United States Post Office as First Class Mail on the date indicated below in an envelope addressed to Assistant Commissioner for Patents, Washington, DC 20231.

4-19-01
Date


Amy Green

Assistant Commissioner for Patents
Washington, DC 20231

PRELIMINARY AMENDMENT

Sir:

Please amend the above-referenced patent application as follows:

In the Specification

Please amend the specification as follows:

Please replace the paragraph at page 9 lines 2 through 4 with the following rewritten paragraph.

--FIGs. 3A to 3F are schematic cross-sectional views which illustrate an embodiment of the method for manufacturing a wiring of a semiconductor device according to the present invention.--

Please replace the paragraph at page 10 lines 8 through 12 with the following rewritten paragraph.

--FIGs. 3A to 3F are schematic cross-sectional views which illustrate an embodiment of the method for manufacturing a wiring of a semiconductor device according to the present invention. The manufacturing method of a wiring of a semiconductor device illustrated in FIG. 2 will be explained in detail with reference to FIGs. 3A to 3F herein below.--

Applicant(s): Lee, et al.
U.S. Serial No.: 09/737,540

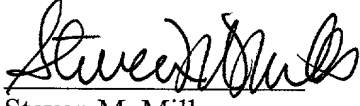
REMARKS

The amendments to the specification are made to clarify the description. No new matter is added to the application.

Attached hereto is a marked-up version of the changes made to the claims by the current Amendment. The attached pages are captioned "Version with Markings to Show Changes Made."

Respectfully submitted,

Date: April 19, 2001
Mills & Onello LLP
Eleven Beacon Street, Suite 605
Boston, MA 02108
Telephone: (617) 994-4900
Facsimile: (617) 742-7774


Steven M. Mills
Registration Number 36,610
Attorney for Applicants

Applicant(s): Lee, et al.
U.S. Serial No.: 09/737,540

Version with Markings to Show Changes Made

In the Specification

The paragraph at page 9 lines 2 through 4 has been amended as follows:

FIGs. 3A to [3G] 3F are schematic cross-sectional views which illustrate an embodiment of the method for manufacturing a wiring of a semiconductor device according to the present invention.

The paragraph at page 10 lines 8 through 12 has been amended as follows:

FIGs. 3A to [3G] 3F are schematic cross-sectional views which illustrate an embodiment of the method for manufacturing a wiring of a semiconductor device according to the present invention. The manufacturing method of a wiring of a semiconductor device illustrated in FIG. 2 will be explained in detail with reference to FIGs. 3A to 3F hereinbelow.

J:\SAM\0134\prelimamend.wpd